In the Specification:

Please amend the paragraph beginning on page 7, line 21 and ending on page 7, line 27 as follows:

-- The through hole 190 is useful during the process of molding the encapsulant material 194 about the package components. The through hole 190 permits passage of molten encapsulant material 194 from adjacent the first surface 186 of the ~~strap~~ **cover portion** 170 through the through hole 190 and into a region adjacent the second surface 188 of the ~~strap~~ **cover portion** 170. Permitting the molten encapsulant material 194 to pass through the hole 190 also helps prevent the strap 122 from being disconnected during the molding process. A portion of the encapsulant material 194 fills the through hole 190. --

Please amend the paragraph beginning on page 8, line 9 and ending on page 8, line 16 as follows:

-- The first surface 186 of the cover portion 170 around the through hole 190 is not covered by the encapsulant material 194, but is exposed in and substantially coplanar and flush with the first surface 196 of the encapsulant material 194. The first surface 186 of the cover portion 170 radiates heat effectively to the exterior, since the first surface 186 is not covered with the encapsulant material 194. Such heat is typically generated at the die 102 and conducted through a thermal path including the flange portion 176 and the connection portion 174 of the strap 122 to the first surface 186 of the ~~strap 122~~ **cover portion 170**, where the heat may be dissipated **from the first surface 186**, such as by radiation. --

Please amend the paragraph beginning on page 8, line 17 and ending on page 8, line 21 as follows:

--Optionally, heat sink structures (not shown), including vertical protrusions, such as heat fins, heat pins, and the like may be attached to, or formed on, the first surface 186 of the ~~strap 122~~ **cover portion 170** to provide additional heat dissipation capability to the package 100. The heat sink structures may be secured on the ~~strap~~ first surface 186 by a thermally conductive adhesive or thermal grease, for example. --

Please amend the paragraph beginning on page 9, line 11 and ending on page 9, line 15 as follows:

--Accordingly, this embodiment provides for multiple thermal paths for dissipation of heat generated at the die 102. Heat may be dissipated through the following exposed surfaces: the first surface 186 **of the cover portion 170** of the strap 122, the second surface 126 of the die pad 104, the second surfaces 136 of the leads 106, the second surface 146 of the lead 114, and the second surfaces 160 of the leads 116-120, among other possibilities. --

Please amend the paragraph beginning on page 9, line 23 and ending on page 10, line 4 as follows:

--FIGS. 4-6 illustrate a semiconductor package 400 in accordance with another embodiment of the present invention. The semiconductor package 400 is similar to the semiconductor package 100 (FIGS. 1-3), and has common features, except as follows. Comparing FIGS. 4 and 5 to FIGS. 1 and 2, **the** first surface 186 of the ~~strap 122~~ **cover portion 170** of package 400 is not exposed through the first surface 196 of the encapsulant material 194, but is encapsulated by the encapsulant material 194. Nonetheless, this embodiment provides for multiple thermal paths for dissipation of heat generated at the die 102. In this embodiment, heat may be dissipated through the following exposed surfaces: the second surface 126 of the die pad 104, the second surfaces 136 of the leads 106, the exposed surface 146 of the lead 114, and the second surfaces 160 of the leads 116-120. Of course, heat will also radiate through the thin layer of encapsulant material 194 over the first surface 186 of the **cover portion 170** of the strap 122. --

Please amend the paragraph beginning on page 10, line 18 and ending on page 10, line 22 as follows:

--Package 700 provides multiple thermal paths for dissipation of heat generated at the die 102. Heat may be dissipated through the following exposed surfaces: the first surface 186 (FIG. 8) **of the cover portion 170** of the strap 122, the second surfaces 136

(FIG. 9) of the leads 106, the second surface 146 (FIG. 9) of the lead 114, and the second surfaces 160 (FIG. 9) of the leads 116, 118, and 120, among other possibilities. --